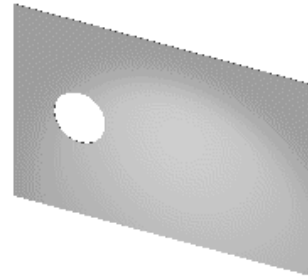


Product- information Type: GL530

Group: Insulating and mounting accessories

Mica wafers

Areas of application (Cases):	TO220
Thickness:	0.05 mm
Material:	Mica
Thermal resistance	1.2 K/W
Temperature rating:	550 °C
Dielectric strength:	2,5 KV



Mica wafers in combination with insulating bushes facilitate the isolated mounting of semiconductors e.g. on heatsinks.

To prevent pockets of air bubbles, the use of thermal compound is recommended.

Thermal resistance Rth (K/W) with thermal compound.

